



H2N4124

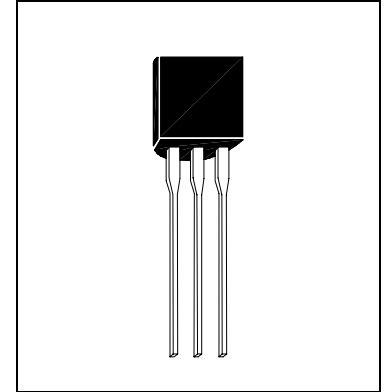
NPN EPITAXIAL PLANAR TRANSISTOR

Description

The H2N4124 is designed for general purpose switching and amplifier applications.

Features

- Complementary to H2N4126
- Low Collector to Emitter Saturation Voltage



Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature..... -55 ~ +150 °C
Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 350 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage 30 V
VCEO Collector to Emitter Voltage 25 V
VEBO Emitter to Base Voltage 5 V
IC Collector Current 200 mA

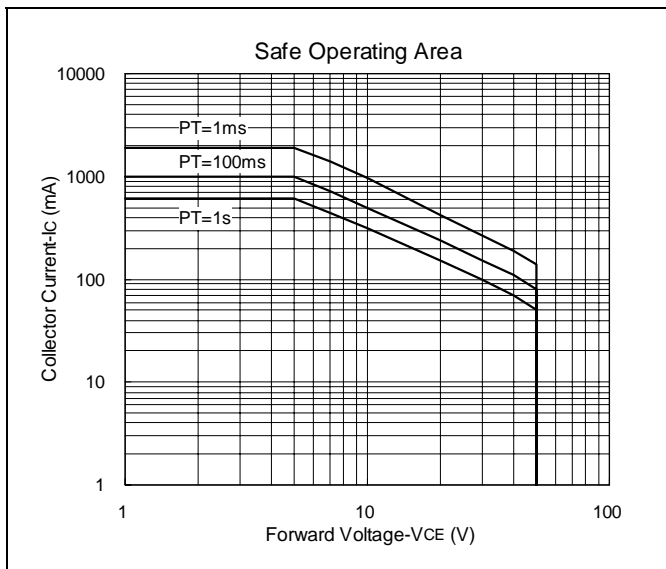
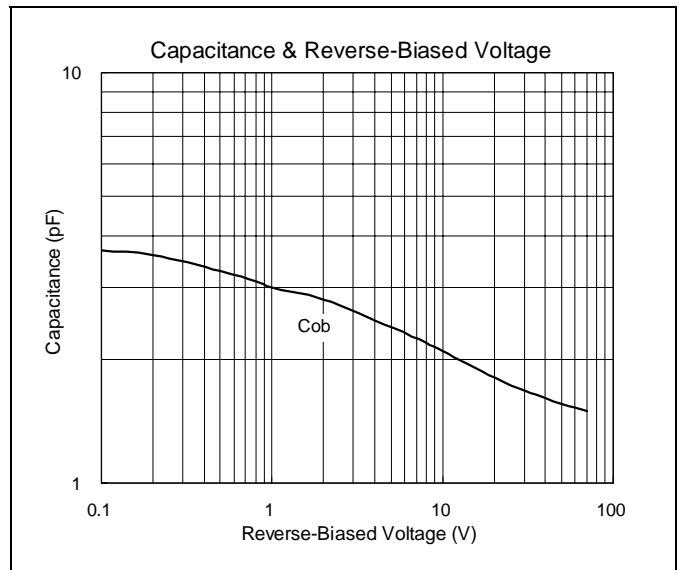
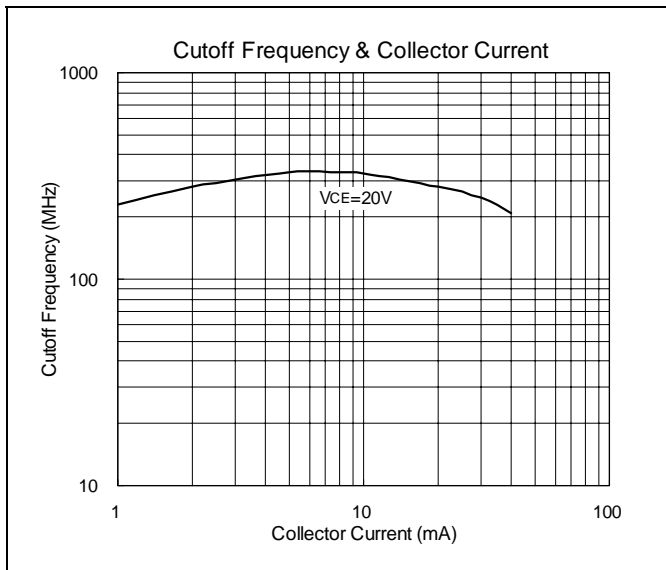
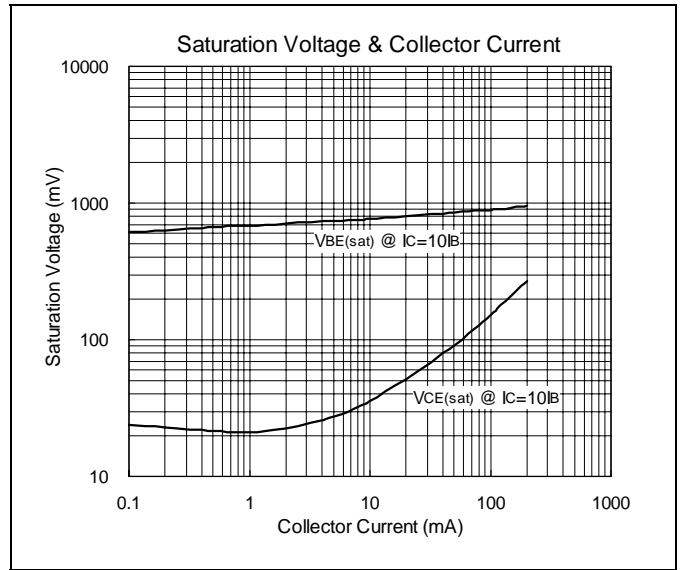
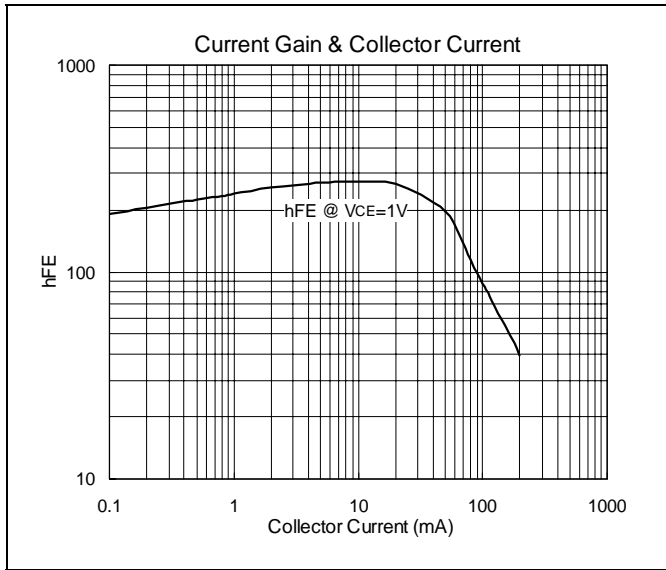
Characteristics (Ta=25°C)

Symbol	Min.	Max.	Unit	Test Conditions
BVCBO	30	-	V	IC=10uA, IE=0
BVCEO	25	-	V	IC=1mA, IB=0
BVEBO	5.0	-	V	IE=10uA, IC=0
ICBO	-	50	nA	VCB=20V, IE=0
IEBO	-	50	nA	VEB=3V, IC=0
*VCE(sat)	-	0.3	V	IC=50mA, IB=5mA
*VBE(sat)	-	950	mV	IC=50mA, IB=5mA
*hFE1	120	360		VCE=1V, IC=2mA
*hFE2	60	-		VCE=1V, IC=50mA
fT	300	-	MHz	VCE=20V, IC=10mA,, f=100MHz
Cob	-	4	pF	VCB=5V, IE=0, f=100MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



Characteristics Curve





TO-92 Dimension

3-Lead TO-92 Plastic Package
HSMC Package Code : A

Marking :

HSMC Logo → □ □ □ □ ← Product Series
 Part Number → □ □ □ □ □ □
 Date Code → □ □ □ □ □ □ ← Rank
 Laser Mark

HSMC Logo
 Product Series
 Part Number → □ □ □ □ □ □
 Ink Mark

Style : Pin 1. Emitter 2. Base 3. Collector

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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